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09912844

Title of Invention:

HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR

SUBSTRATE

First Named Inventor:

Maximilian Biberger

Domestic/Foreign Application:

Domestic Application

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Attorney Docket Number:

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TRANSMITTAL

Tipe tronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE

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Maximilian A. Biberger

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Submitted by:			
Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney	

Documents being submitted

Files

us-ids

SSI00501B-usidst.xml

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Comments



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention

HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE

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Search string:

(5193560 or 5195878 or 5213485 or 5221019 or 5222876 or 5224504 or 5236669 or 5240390 or 5243821 or 5246500 or 5251776 or 5280693 or 5285352 or 5288333 or 5339844 or 5370741 or 5412958 or 5433334 or 5447294 or 5503176 or 5505219 or 5509431 or 5571330 or 5589224 or 5621982 or 5629918 or 5644855 or 5649809 or 5656097 or 5669251 or 5702228 or 5706319

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US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Remarks

Note: Remarks are not for responding to an office action.

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Signature

Examiner Name	Date		